



OVERVIEW OF PLASTIC SUBSTRATES FOR PRINTED ELECTRONICS

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Special thanks to:
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Bill MacDonald

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Market Knowledge

Customer Success

Technical Capability

Overview

- Ø Flexible Electronics Today
- Ø Development Highlights
- Ø Industry Challenges
- Ø Conclusion

Printed Electronics Exist Today

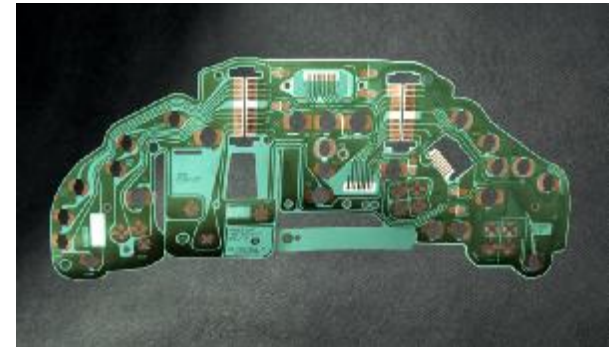
Ø Membrane Touch Switch

- q Automotive MTS, eg seat sensors
- q PEN allows higher temperature specifications



Ø Flexible Printed Circuits / Flat Flexible Cable

- q Automotive wiring harness replacement with flat cables
- q LED rear light clusters and daylight running lights



Ø Optical Displays

- q Electroluminescent lamps and next generation displays

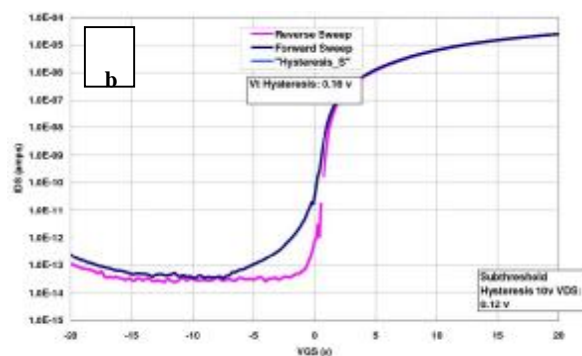
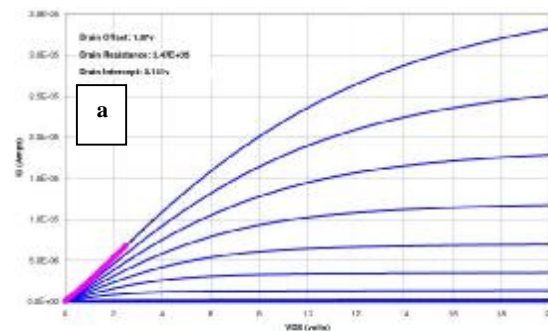


Printed Electronics Today



- Security, ID, health cards
- Passports
- Protective Labels
- Medical Test strips

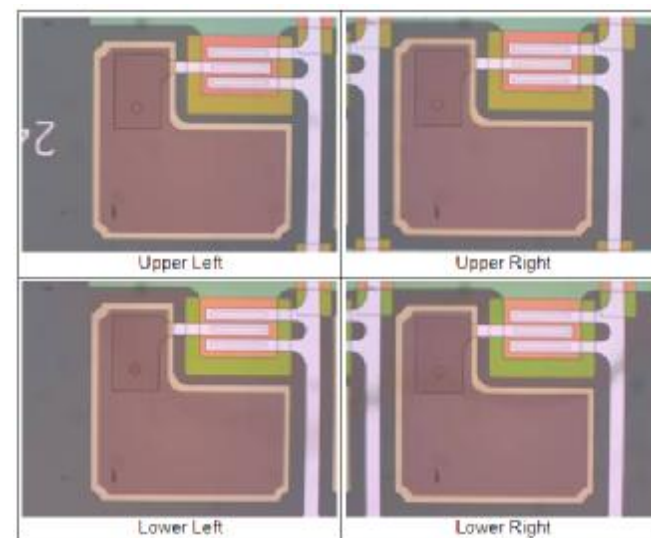
Parameter	FDC
Max. Process Temperature	180 °C (flex)
Saturation Mobility (cm ² /V-s)	0.7
ON/OFF Ratio	2 x 10 ⁹
Drive Current (μA)	30
Threshold Voltage (V)	1.0



Typical output (a) and transfer (b) characteristics of a-Si TFTs fabricated on PEN



3.8-in QVGA E-Ink Display on PEN

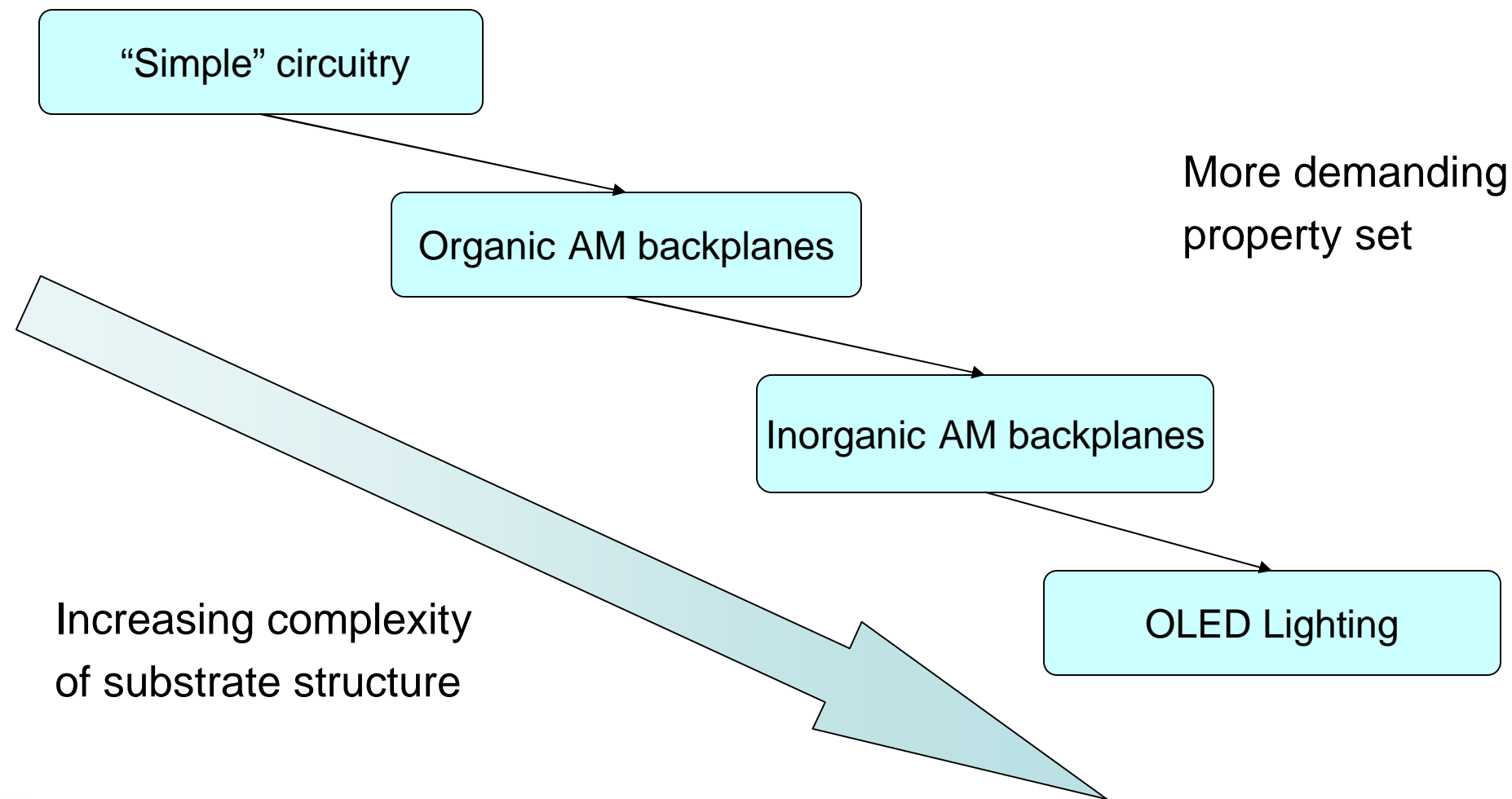


TFT pixels at 4 corners of 3.8-in QVGA



Developments

Factors Influencing Substrate Choice-Property Set

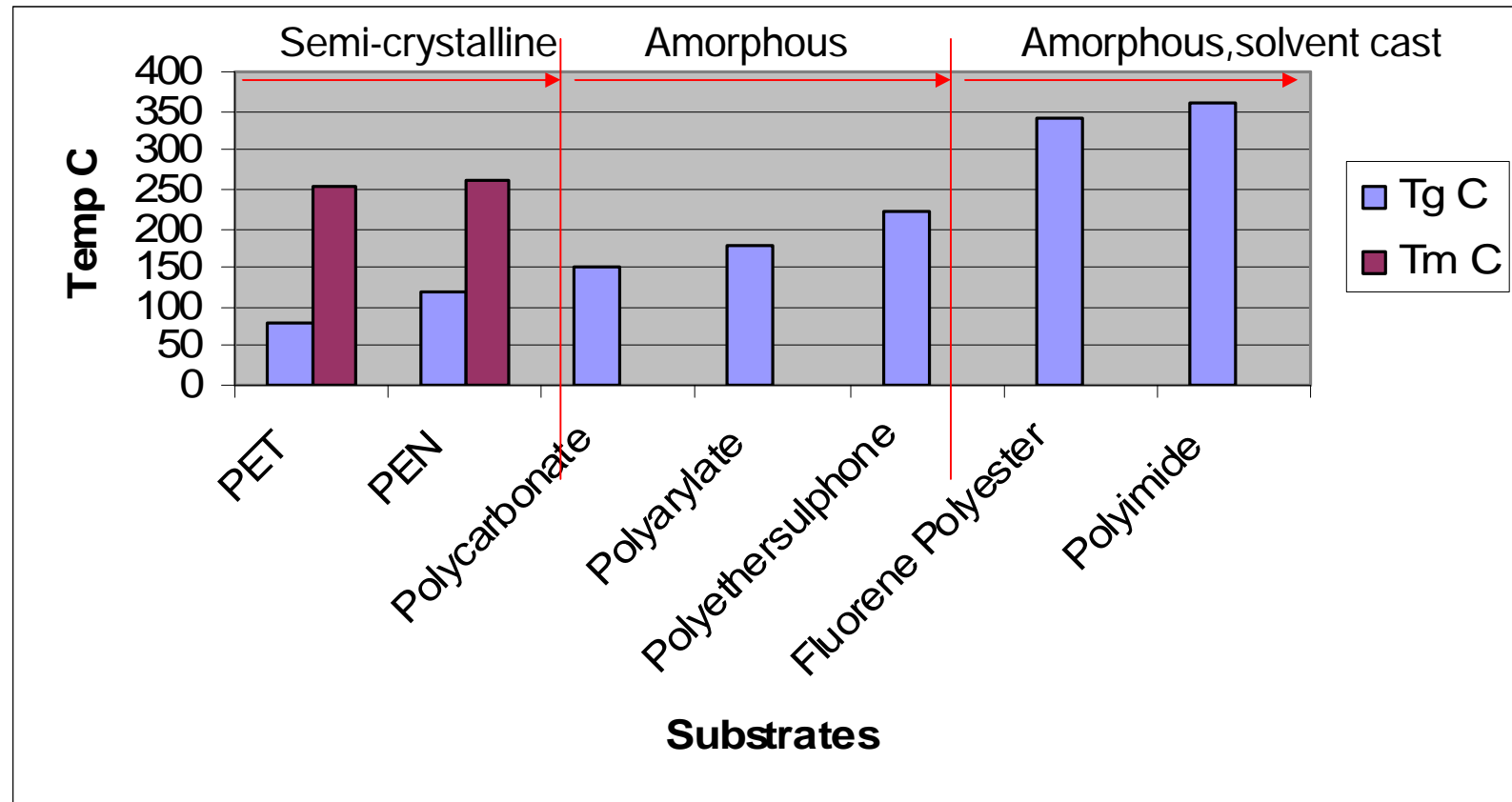


Key Challenges for Engineered Substrates into Flexible Electronics Applications

- Ø Low Coefficient of Thermal Expansion
- Ø Low Shrinkage
- Ø Upper Temperature for Processing
- Ø Surface smoothness
- Ø Barrier
- Ø Solvent Resistance
- Ø Moisture Resistance
- Ø Clarity
- Ø Rigidity
- Ø Conductive layers
- Ø Commercial availability
 - q Development started in late "90's" primarily for OLED and LCD applications
- Ø Substrates for the more demanding applications are likely to be multilayer structures containing both organic and inorganic layers

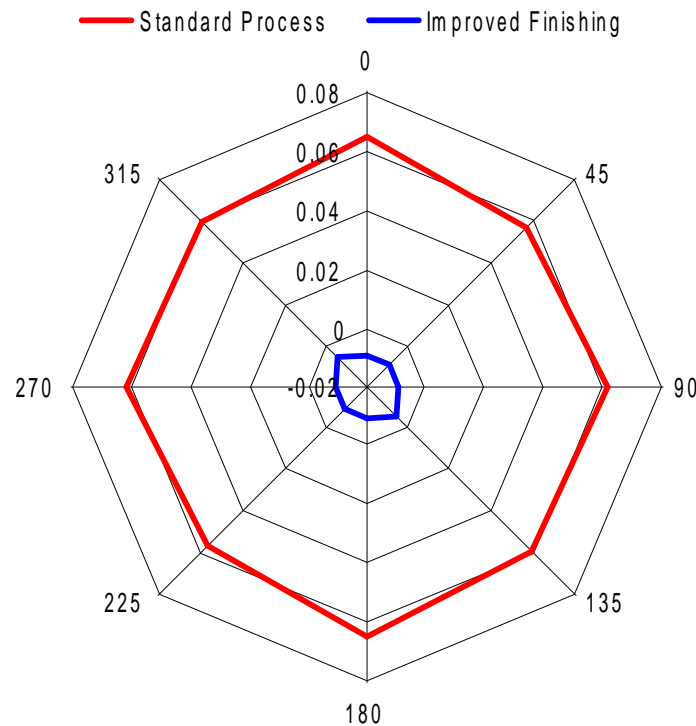
Factors Influencing Film Choice-Substrate Properties

Films grouped by thermal properties

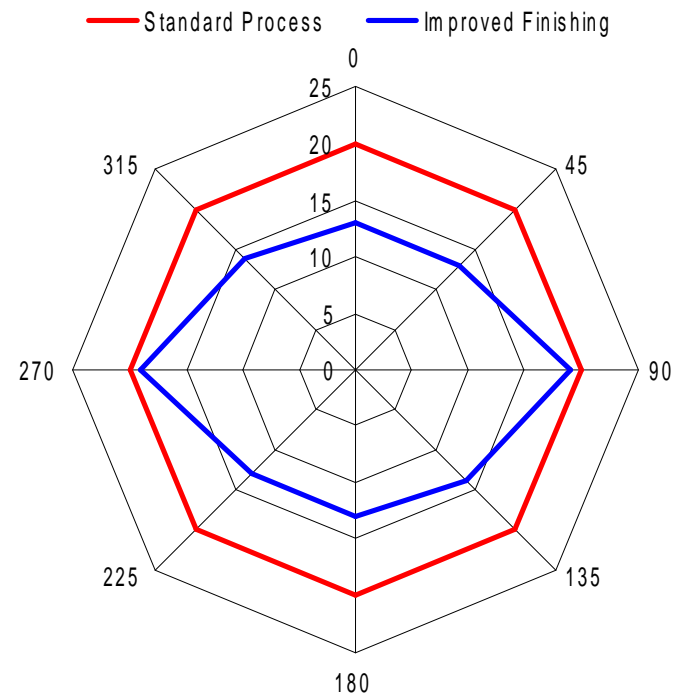


Improved Process for Heat Treating

- Ø Thermal finishing cycle virtually remove shrinkage: -0.01% at 180°C , 30' (left graph)
- Ø CLTE is reduced by 25%: $20\text{ppm/K} \rightarrow 15\text{ppm/K}$ (right graph)

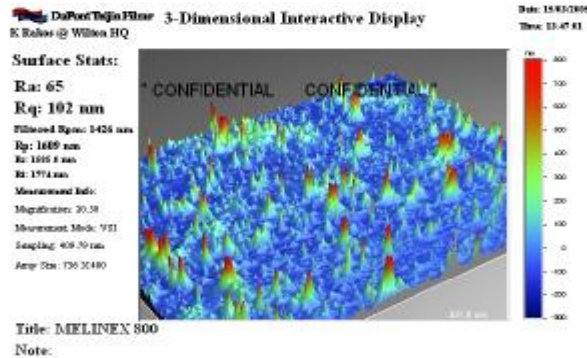


Shrinkage % (180°C , 30min) vs. direction in plane of Teonex® PEN film ($0^{\circ}=\text{MD}$)

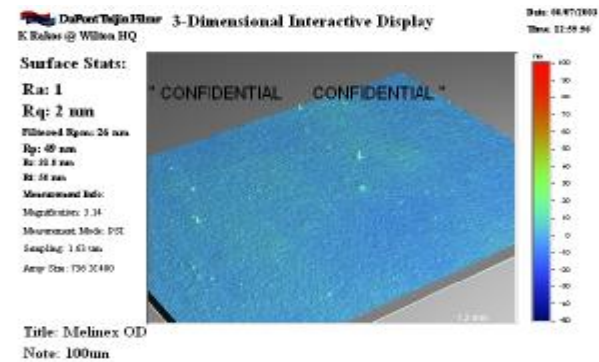


CLTE (ppm/K) vs. direction in plane of Teonex® PEN film ($0^{\circ}=\text{MD}$)

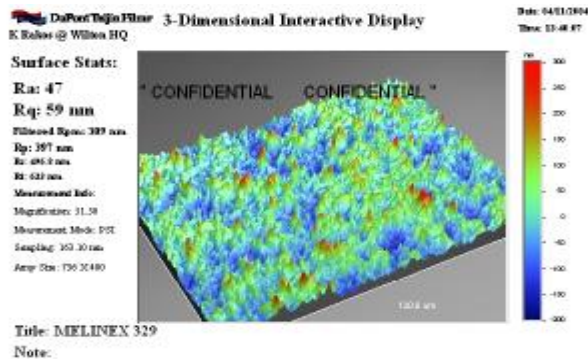
Surface Roughness from Additive Packages



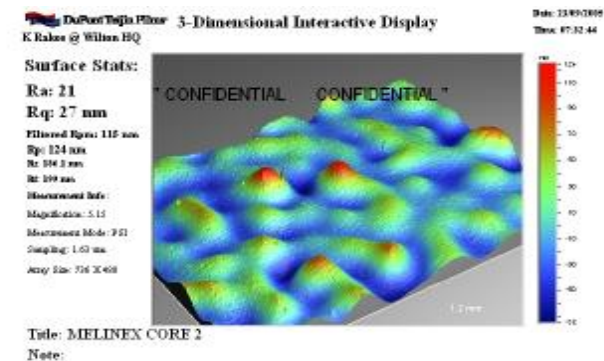
Standard Packaging Film



“Electronics” Grade Film

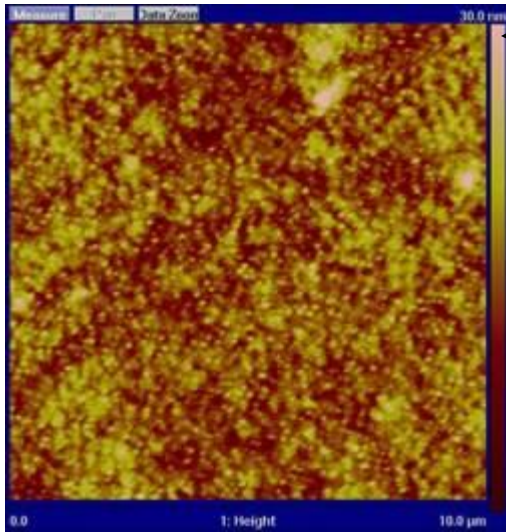


White Opaque Film



Laminating Film

Optimized Surface for Fine Features



30nm

AFM - 10 micron square
ST506 surface

Amplitudes +/- 30nm



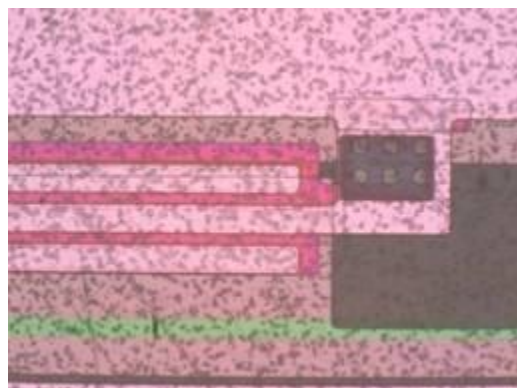
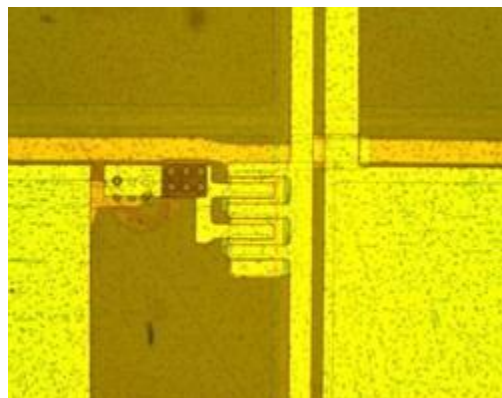
20nm

AFM - 10 micron square
Planarised ST506 surface

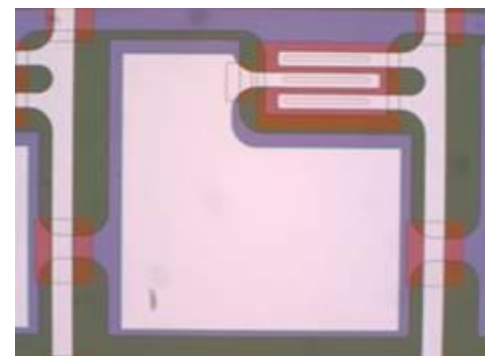
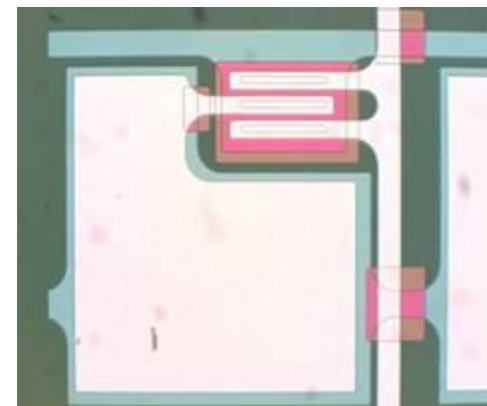
Very smooth - within the noise floor

Does Roughness Impact Circuitry?

QVGA aSi TFT array built on PEN



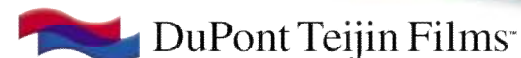
Planariser
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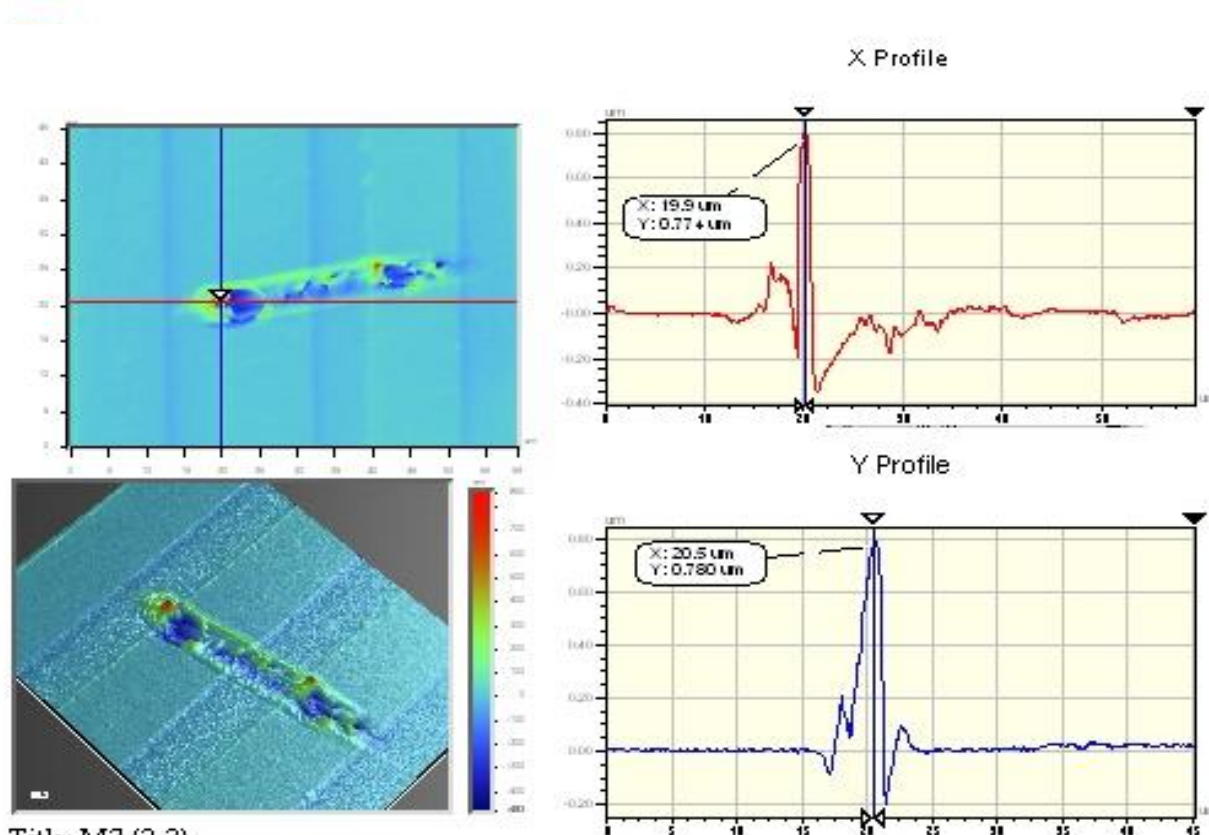
Uncoated Heat stabilised PEN

Planarised Heat stabilised PEN

Slide shown courtesy of Flexible Display
Centre, ASU



Challenge from Scratches



Title: M7 (2-3)

Note:

Scratches and Surface Debris can easily cause trace breaks.

Industry Challenges

- Ø For economics, machine scale is large, producing millions of square meters an hour.
 - q Need large scale opportunities
 - q Today, must leverage products for other markets to meet small scale demands
- Ø Measurement
 - q Size of defects and density becoming tighter
 - q Measurement systems do not exist for volume QC, must rely on spot measurement
- Ø Global Supply Chains
 - q US producers must design for “best in class” global standards.
 - q Aggressive investment in Asia for the LCD industry

Summary

- Ø Development of Films for Printed Electronics have been ongoing for many years, leveraged from other industries.
- Ø Choice of film type and thickness is crucial.
 - q Important to pick the right film for the application.
- Ø Control of surface quality is critical.
 - q Critical to understand the type of surface defects which impact device manufacture and performance.
- Ø Global supply chains are a given
 - q “Best in class” assets need investment and on-going re-investment

Thank You



Melinex[®] polyester film **Mylar[®]** polyester film
Teijin[®]Tetoron[®] polyester film **Teonex[®]** PEN polyester film

*How many times a day do you rely on PET and PEN
polyester films from DuPont Teijin Films?*

